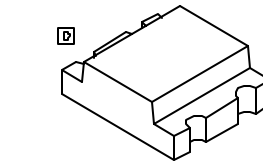
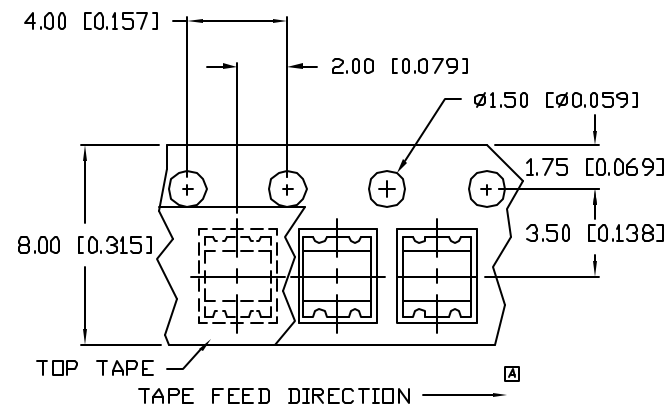
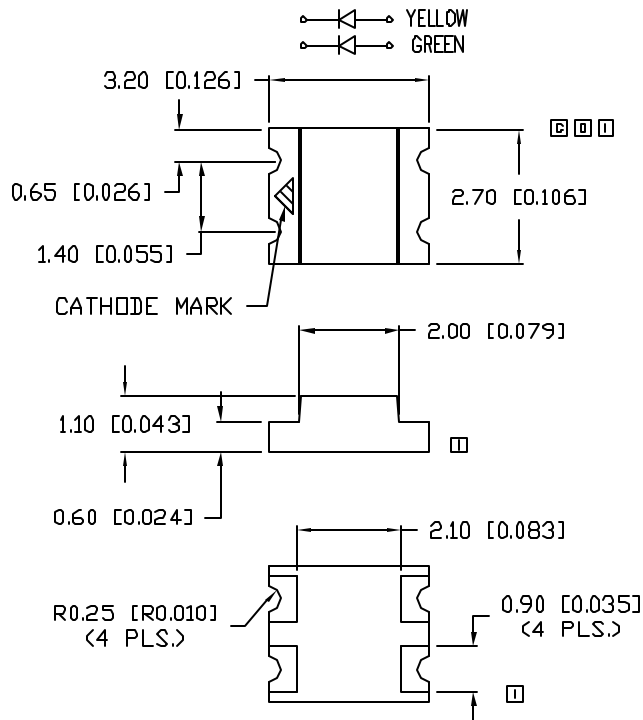
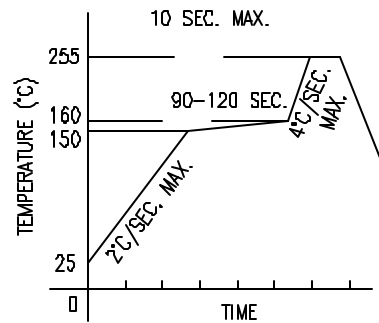


UNCONTROLLED DOCUMENT

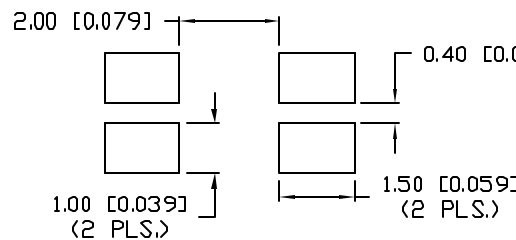


LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.038), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=+DECIMAL PRECISION MAX.=+0.00 -0.00

PART NUMBER
SML-LX1210YGC-TR

REV.
I

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	ADDED TAPE W/POLARITY AND DIRECTION.	11.6.95
B	E.C.N. #10324.	3.17.97
C	E.C.N. #10404, & #10BRDR & REDRAWN.	5.22.98
D	E.C.N. #10695	1.4.01
E	E.C.N. #10834.	1.24.02
F	E.C.N. #10972.	3.25.03
G	E.C.N. #11014.	7.11.03
H	E.C.N. #11148.	2.7.05
I	E.C.N. #11479.	2.22.08

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585 (YELLOW) 565 (GREEN)		nm	
FORWARD VOLTAGE (Y/G)		2.1/2.2	2.5/2.6	V _f	
REVERSE VOLTAGE	5.0			V _r	I _r =100μA
AXIAL INTENSITY		10		mcad	I _f =20mA
VIEWING ANGLE		140		2x theta	
EMITTED COLOR:	YELLOW/GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		150	mA
STEADY CURRENT		25	mA
POWER DISSIPATION		65	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING TEMP.		-25 TO +85	°C
STORAGE TEMP.		-30 TO +85	°C

* $t < 10\mu\text{s}$

NOTES:

1. THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.
2. LOCATION FOR CATHODE MARK CAN BE EITHER ON THE TOP OR BOTTOM OF THE PART.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

UNCONTROLLED DOCUMENT

REV.

I

PART NUMBER

SML-LX1210YGC-TR

2.7mm x 3.2mm P.C.B. SURFACE MOUNT LED,
DUAL YELLOW/GREEN CHIPS, WATER CLEAR LENS.

CONFIDENTIAL INFORMATION

THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.

RELIABILITY NOTE

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



US WEB: www.lumex.com
TW WEB: www.lumex.com.tw

DRAWN BY: JD	CHECKED BY:	APPROVED BY:	DATE: 6.21.95
			PAGE: 1 OF 1
			SCALE: N/A